

AMENDMENTS TO THE SPECIFICATION:

Please replace the first full paragraph beginning on page 2, line 9 with the following rewritten version:

An interposer board is mass produced generally using a thick film technique (such as coating technique, printing technique, etc.), thin film technique (such as deposition technique, sputtering technique, etc.), etc., the interposer board being produced by forming extended electrodes on a base member, an IC chip being mounted on the base member, each of the extended electrodes being connected to corresponding electrode of the IC chip. That is, a plurality of interposer ~~board~~ boards is formed on an interposer board tape. ~~An example~~ Examples of the interposer board tape ~~[[is]]~~ are illustrated in ~~Fig.~~ Figs. 9 and 10.

Please replace the fourth sub-paragraph beginning on page 7, line 9 with the following rewritten version:

Figures 9 and 10 are schematic top views of an interposer board ~~tape tapes~~, ~~(a)~~ Figure 9 illustrates an example in which a plurality of row of interposer boards ~~are~~ is formed, while ~~(b)~~ Figure 10 illustrates an example obtained by slitting and cutting only one row from ~~(a)~~ the interposer board tape of Figure 9.